

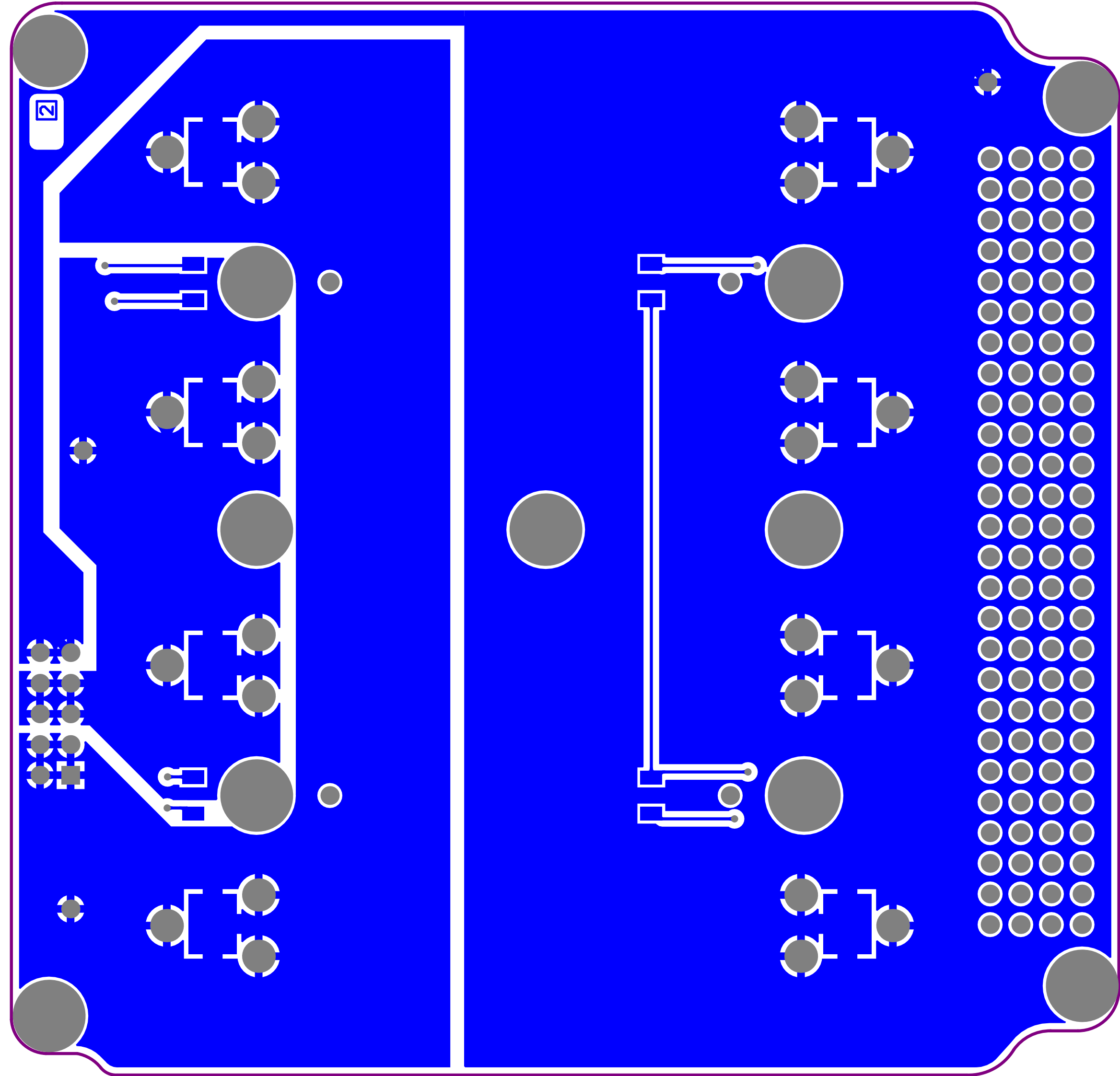
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric Core	FR-4	1,500mm	4,2	
5	Bottom Layer	Copper	0,035mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base 10Z:
 - PCB Material: Prepeg FR4—Standard
 - PCB Tickness: 1.6mm
 - PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
 - Soldermask Color: Green
 - Vias: Force Complete Tenting
 - Special: Stack—up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components



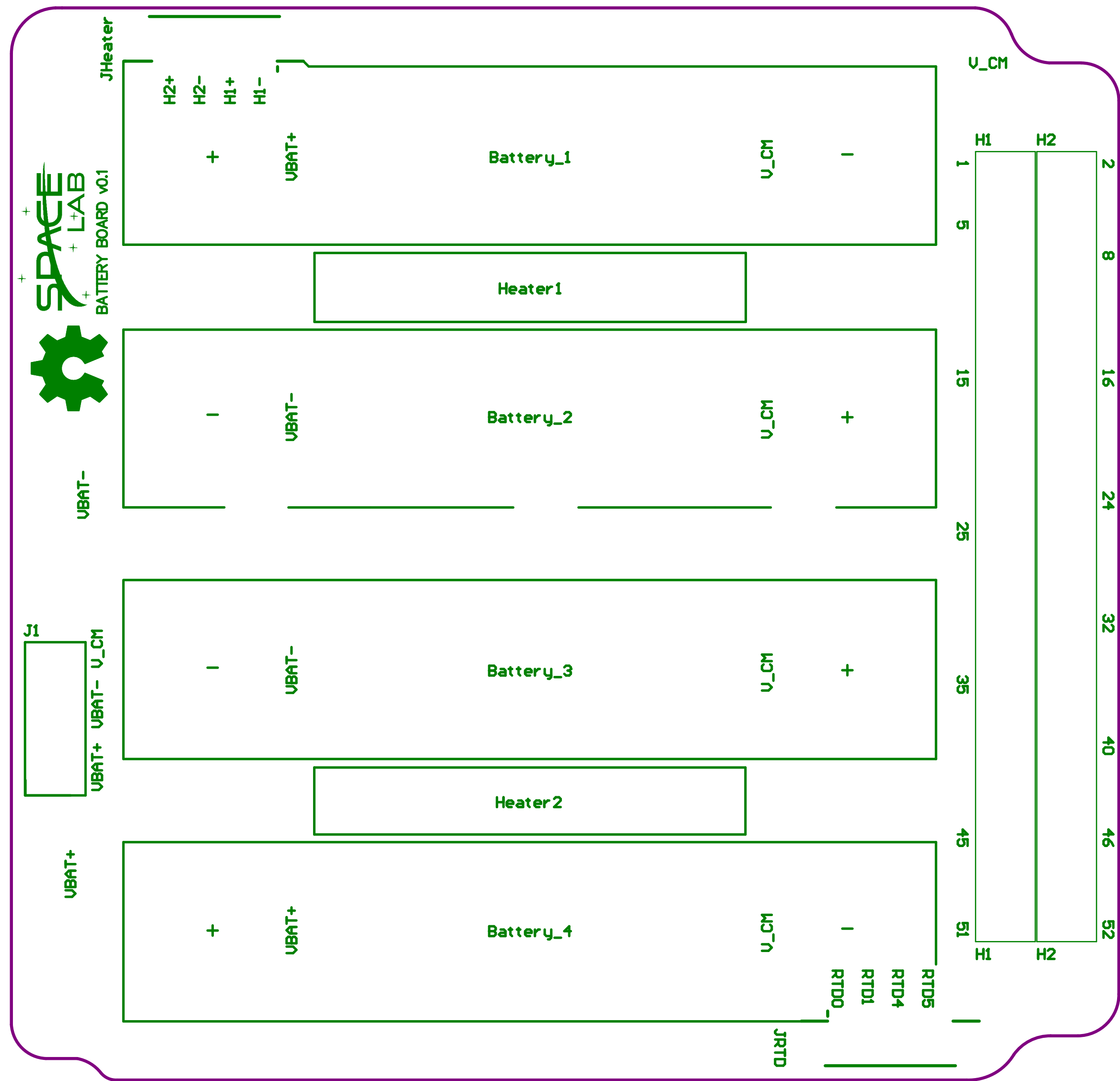
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric Core	FR-4	1,500mm	4,2	
5	Bottom Layer	Copper	0,035mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base 10Z:
 - PCB Material: Prepeg FR4—Standard
 - PCB Tickness: 1.6mm
 - PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
 - Soldermask Color: Green
 - Vias: Force Complete Tenting
 - Special: Stack—up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom availiable
- Check BOM for not placed components



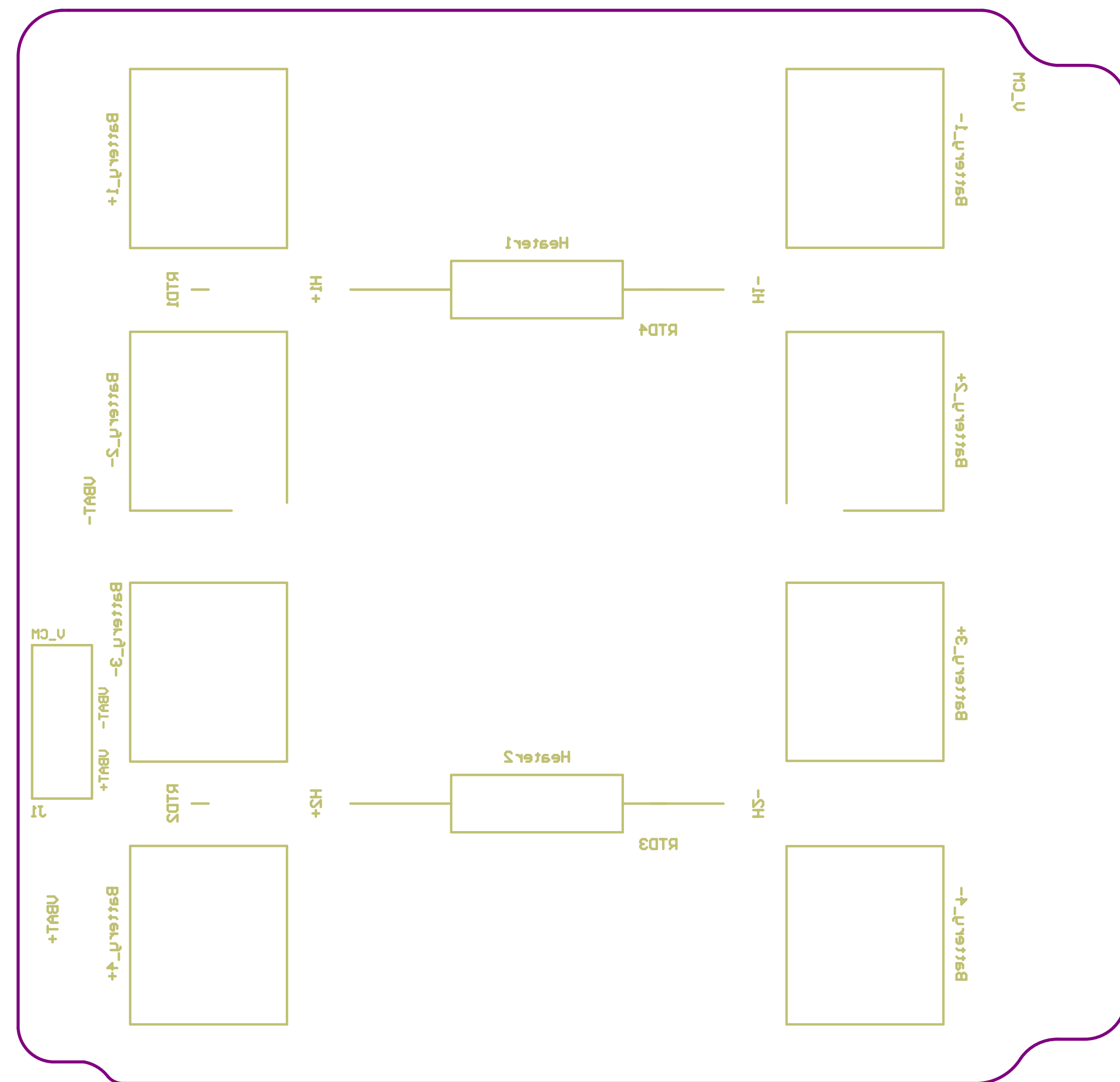
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric Core	FR-4	1,500mm	4,2	
5	Bottom Layer	Copper	0,035mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base 10Z:
 - PCB Material: Prepeg FR4–Standard
 - PCB Tickness: 1.6mm
 - PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
 - Soldermask Color: Green
 - Vias: Force Complete Tenting
 - Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric Core	FR-4	1,500mm	4,2	
5	Bottom Layer	Copper	0,035mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

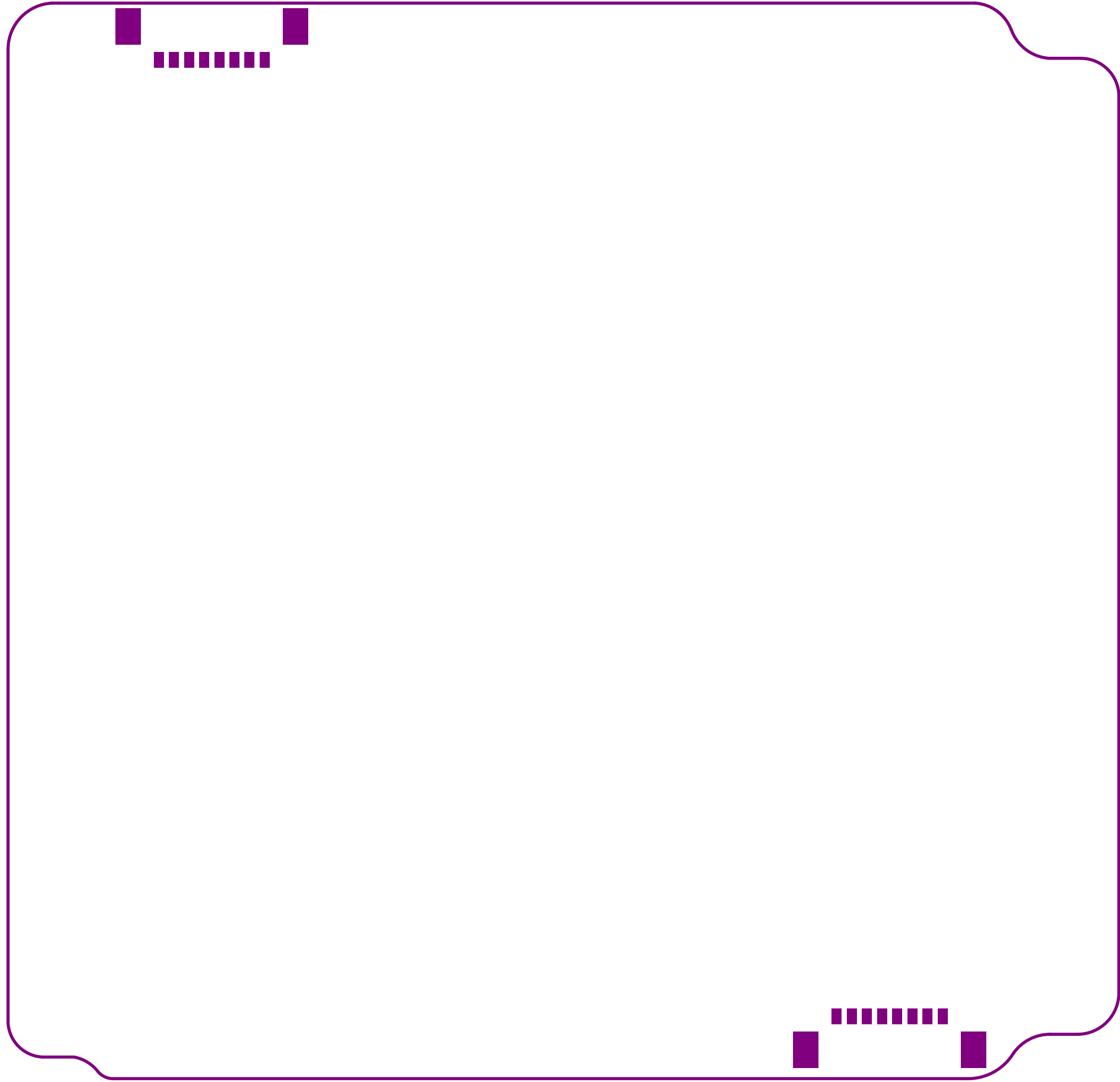
Fabrication specifications:

- Copper base 10Z:
- PCB Material: Prepeg FR4—Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack—up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components





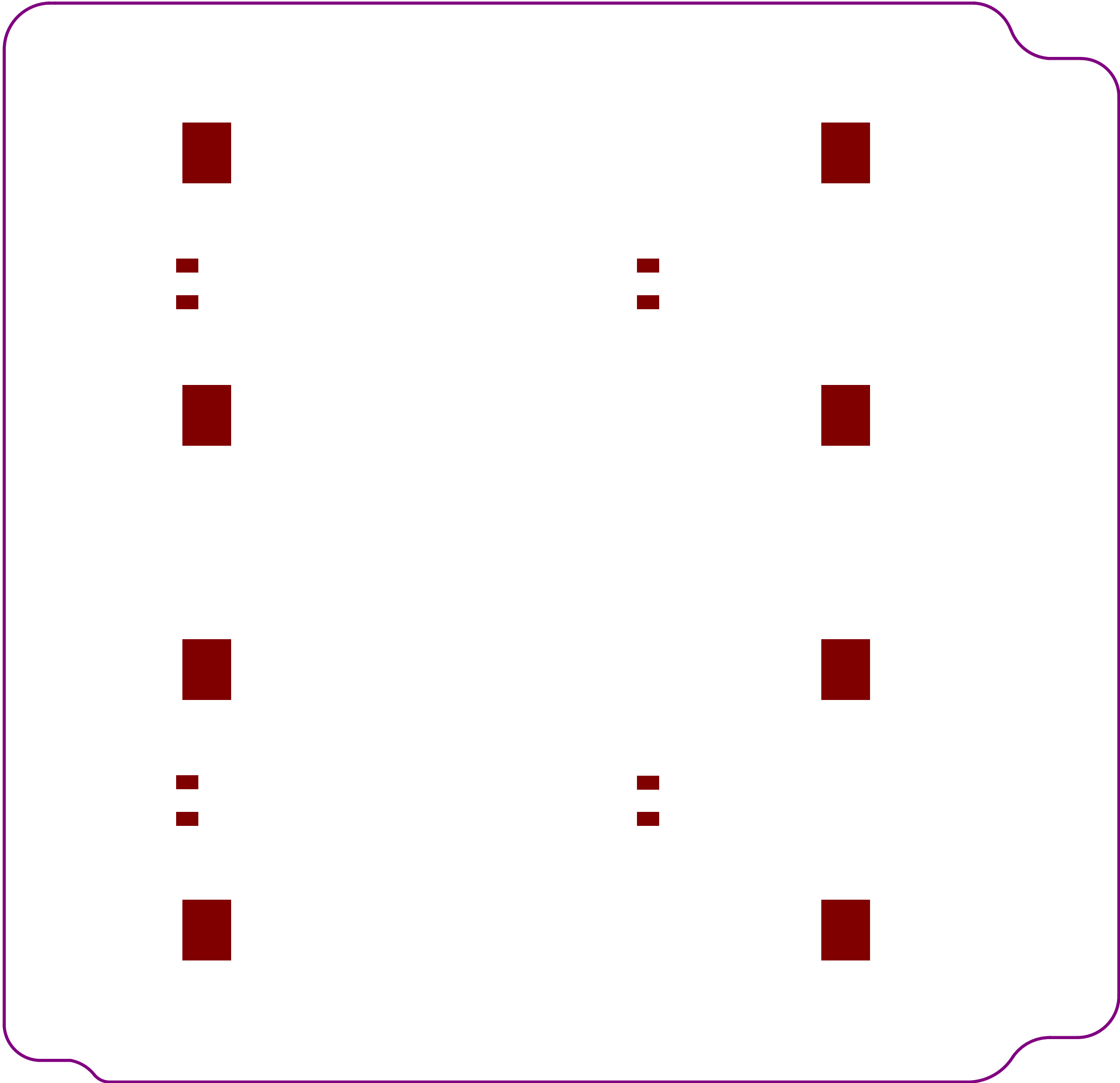
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric Core	FR-4	1,500mm	4,2	
5	Bottom Layer	Copper	0,035mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base 10Z:
 - PCB Material: Prepeg FR4–Standard
 - PCB Tickness: 1.6mm
 - PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
 - Soldermask Color: Green
 - Vias: Force Complete Tenting
 - Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components



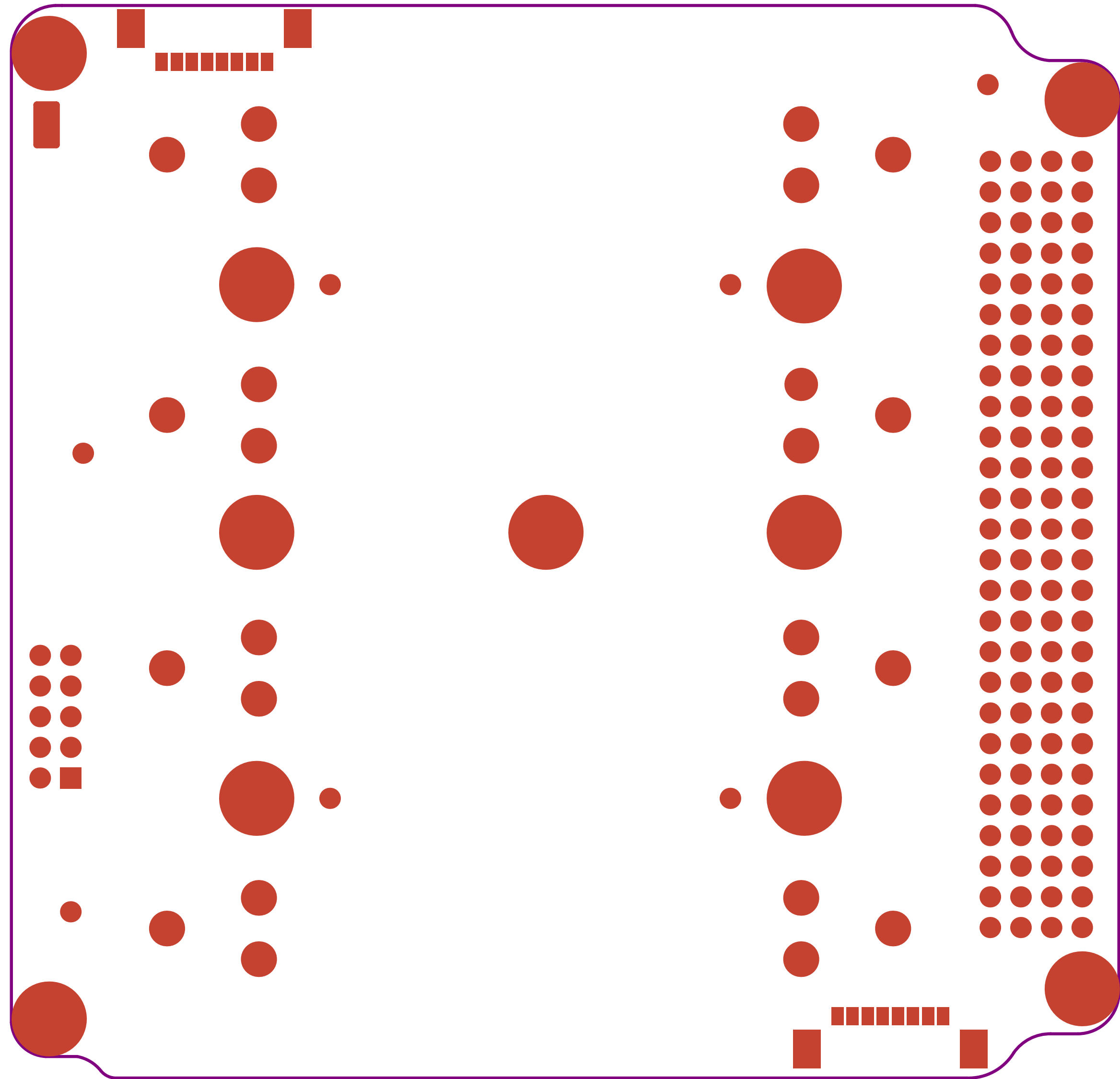
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric Core	FR-4	1,500mm	4,2	
5	Bottom Layer	Copper	0,035mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base 10Z:
 - PCB Material: Prepeg FR4–Standard
 - PCB Tickness: 1.6mm
 - PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
 - Soldermask Color: Green
 - Vias: Force Complete Tenting
 - Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components



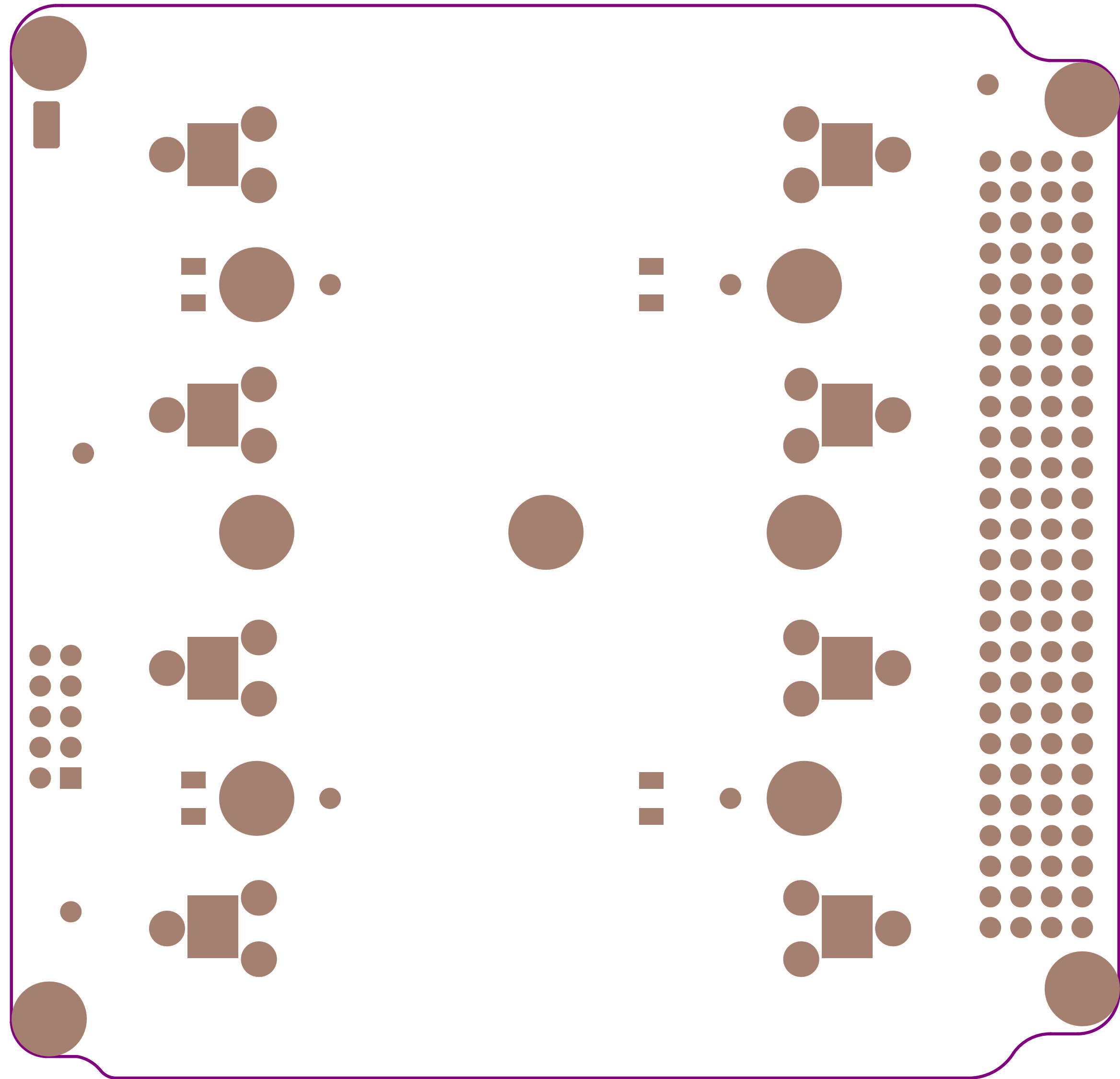
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric Core	FR-4	1,500mm	4,2	
5	Bottom Layer	Copper	0,035mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base 10Z:
 - PCB Material: Prepeg FR4–Standard
 - PCB Tickness: 1.6mm
 - PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
 - Soldermask Color: Green
 - Vias: Force Complete Tenting
 - Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components



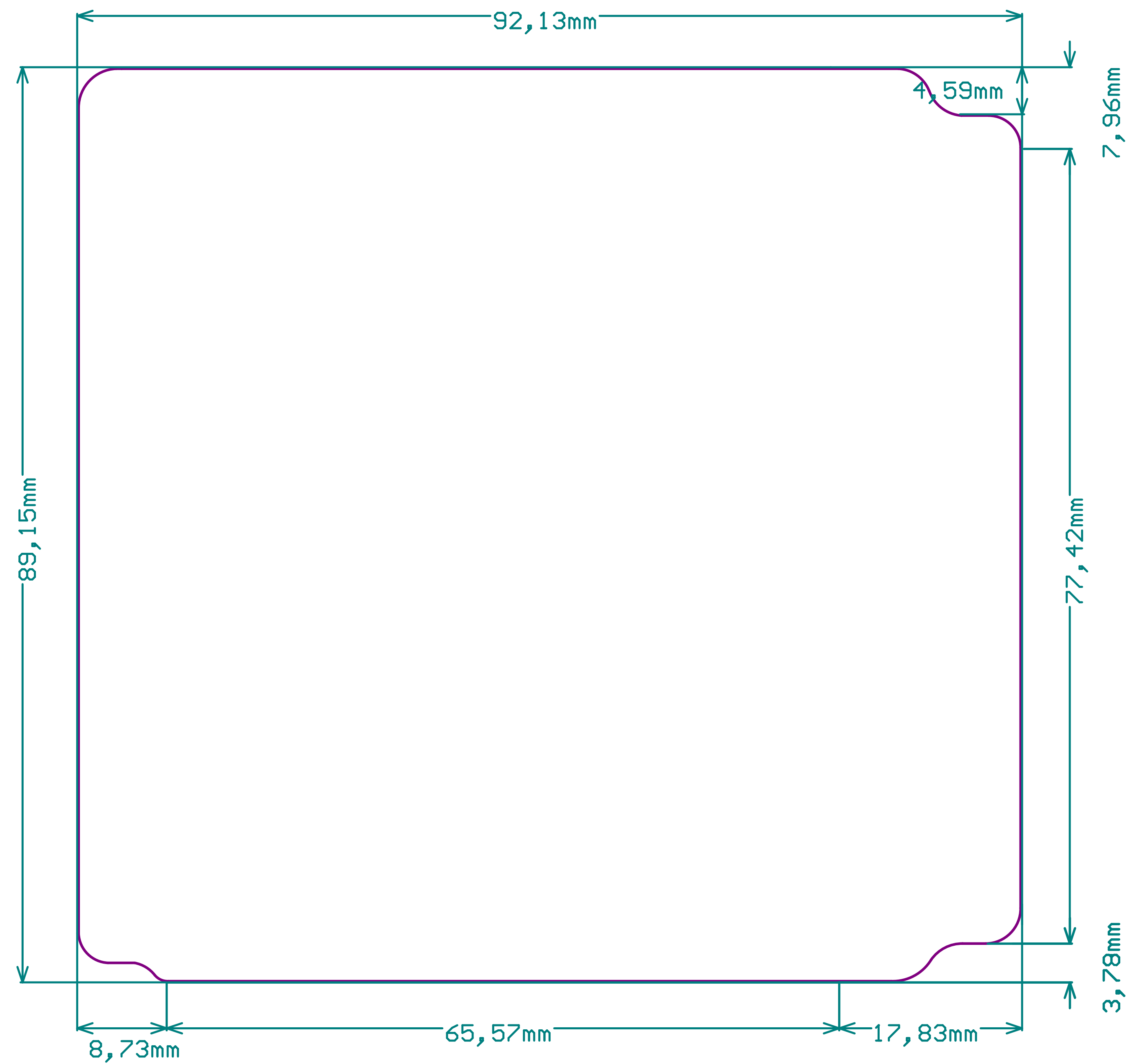
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric Core	FR-4	1,500mm	4,2	
5	Bottom Layer	Copper	0,035mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base 10Z:
 - PCB Material: Prepeg FR4–Standard
 - PCB Tickness: 1.6mm
 - PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
 - Soldermask Color: Green
 - Vias: Force Complete Tenting
 - Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components



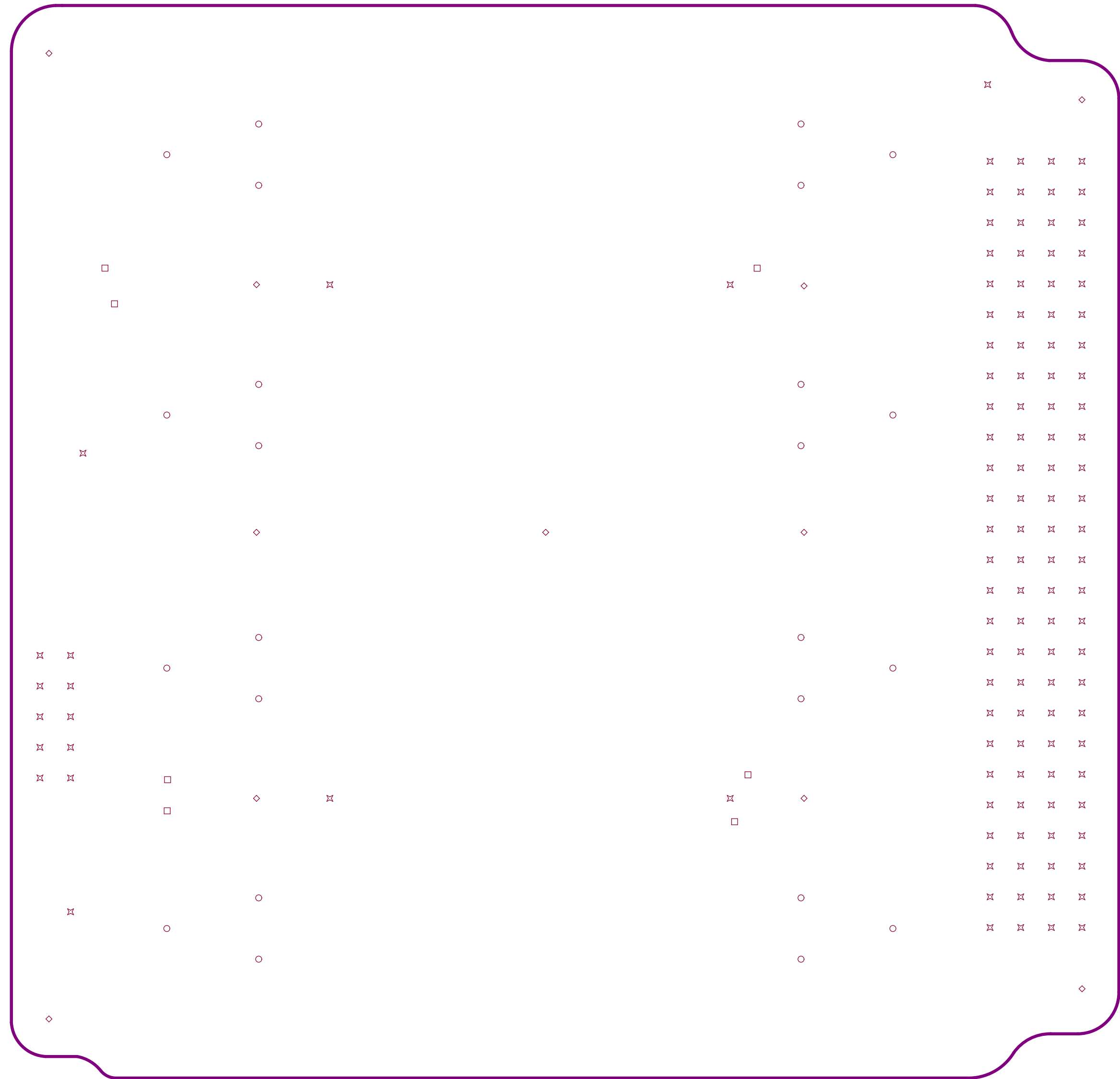
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric Core	FR-4	1,500mm	4,2	
5	Bottom Layer	Copper	0,035mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base 10Z:
 - PCB Material: Prepeg FR4—Standard
 - PCB Tickness: 1.6mm
 - PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
 - Soldermask Color: Green
 - Vias: Force Complete Tenting
 - Special: Stack—up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric Core	FR-4	1,500mm	4,2	
5	Bottom Layer	Copper	0,035mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
□	7	11,81mil (0,300mm)	PTH	Round	Top Layer - Bottom Layer	Via
◇	11	125,98mil (3,200mm)	PTH	Round	Top Layer - Bottom Layer	Pad
○	24	72,05mil (1,830mm)	PTH	Round	Top Layer - Bottom Layer	Pad
⊗	121	39,37mil (1,000mm)	PTH	Round	Top Layer - Bottom Layer	Pad
	163 Total					

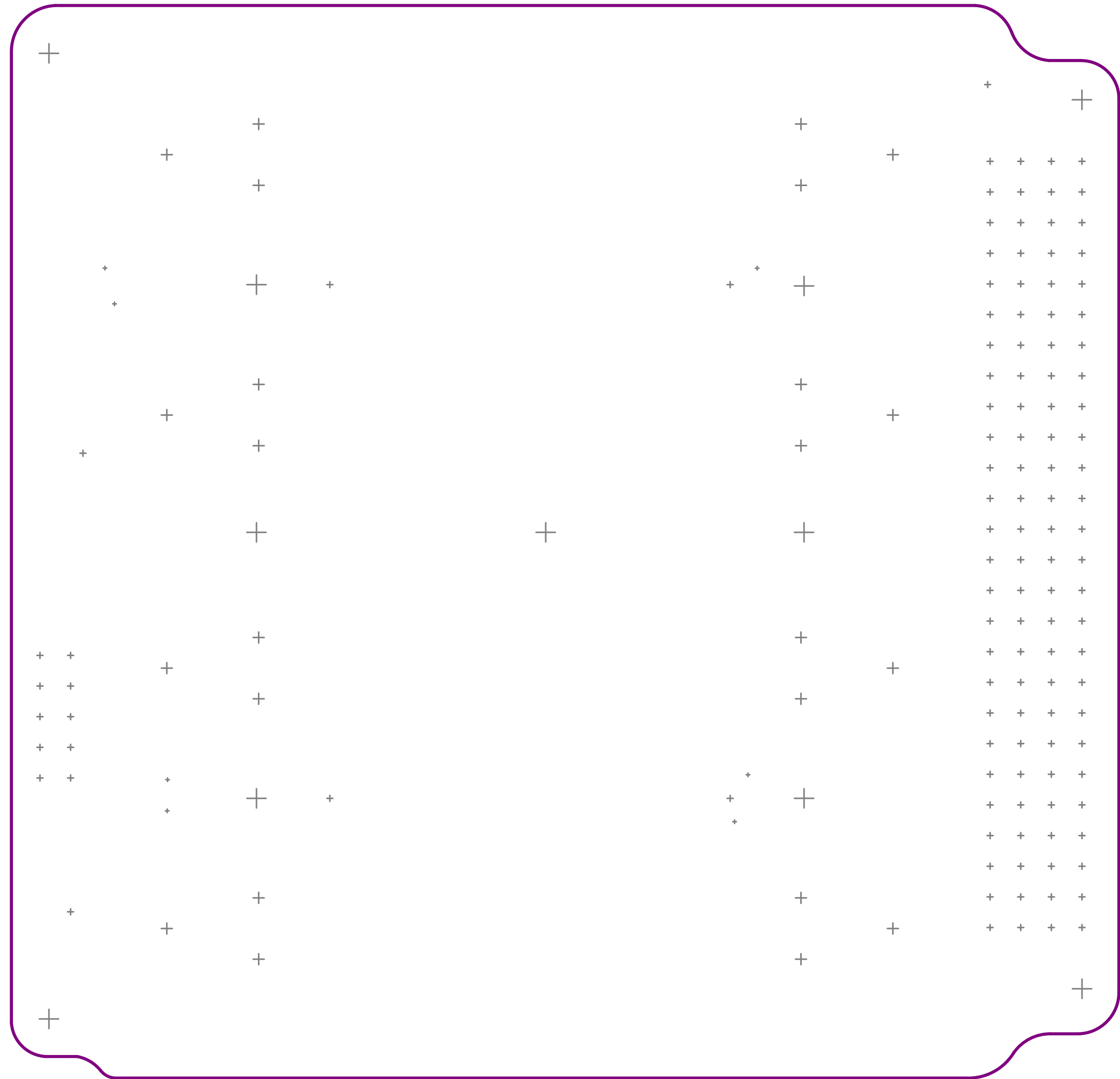
Fabrication specifications:

- Copper base 10Z:
 - PCB Material: Prepeg FR4—Standard
 - PCB Tickness: 1.6mm
 - PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
 - Soldermask Color: Green
 - Vias: Force Complete Tenting
 - Special: Stack—up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components





Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric Core	FR-4	1,500mm	4,2	
5	Bottom Layer	Copper	0,035mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base 10Z:
 - PCB Material: Prepeg FR4–Standard
 - PCB Tickness: 1.6mm
 - PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
 - Soldermask Color: Green
 - Vias: Force Complete Tenting
 - Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components